

SOLDER PASTE

# LEAD-FREE HIGH TEMPERATURE SOLDER PASTE



Sn99/Ag0.3/Cu0.7

Melting point 217°C



# Product Usage



## TIN PASTE

<b>Model</b>	BST-705A
<b>Name</b>	Lead-free high temperature solder paste
<b>Composition</b>	Sn99/Ag0.3/Cu0.7
<b>Melting point</b>	217°C
<b>G.W.</b>	50g
<b>Granule</b>	20~38μm
<b>Size</b>	φ50*16mm

Sn99/Ag0.3/Cu0.7

Lead-free high temperature melting point

217°C





Low residue

Fine grain

Rapid welding

Solder spot bright

# Welding requirements for a wide range of products



SMT  
patch



LED  
patch



BGA  
welding

# Product Size



G.W.:50g

